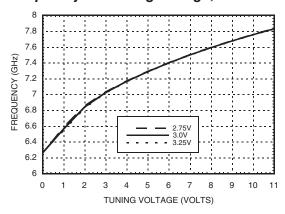


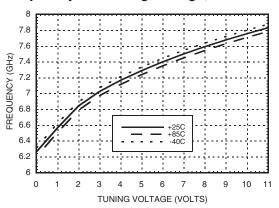


MMIC VCO w/ BUFFER AMPLIFIER, 6.8 - 7.4 GHz

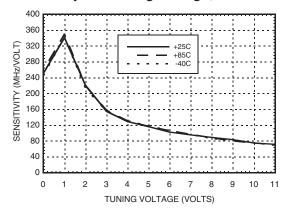
Frequency vs. Tuning Voltage, T= 25°C



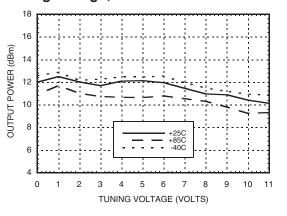
Frequency vs. Tuning Voltage, Vcc= +3V



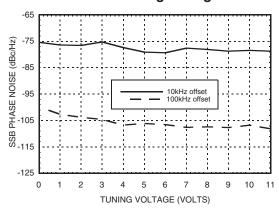
Sensitivity vs. Tuning Voltage, Vcc= +3V



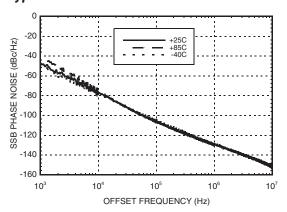
Output Power vs.
Tuning Voltage, Vcc= +3V



Phase Noise vs. Tuning Voltage



Typical SSB Phase Noise @ Vtune= +5V





MMIC VCO w/ BUFFER AMPLIFIER, 6.8 - 7.4 GHz

Absolute Maximum Ratings

Vcc	+3.5 Vdc
Vtune	0 to +11V
Channel Temperature	135 °C
Continuous Pdiss (T = 85°C) (derate 6.31 mW/°C above 85°C)	315 mW
Thermal Resistance (R _{TH}) (junction to package base)	158 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Typical Supply Current vs. Vcc

Vcc (V)	Icc (mA)
2.75	70
3.0	80
3.25	90

Note: VCO will operate over full voltage range shown above.



Outline Drawing

BOTTOM VIEW -.016 [0.40] REF .008 [0.20] MIN 19 PIN 1 HNNN XXXX 13 6 **EXPOSED** LOT NUMBER GROUND **PADDLE** 1.00 0.80 SQUARE .000 1. LEADFRAME MATERIAL: COPPER ALLOY 2. DIMENSIONS ARE IN INCHES [MILLIMETERS] SEATING PLANE 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE. .003[0.08] C

-C-

- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOT FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC505LP4	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H505 XXXX
HMC505LP4E RoHS-compliant Low Stress Injection Molded Plastic		100% matte Sn	MSL1 [2]	H505 XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX





MMIC VCO w/ BUFFER AMPLIFIER, 6.8 - 7.4 GHz

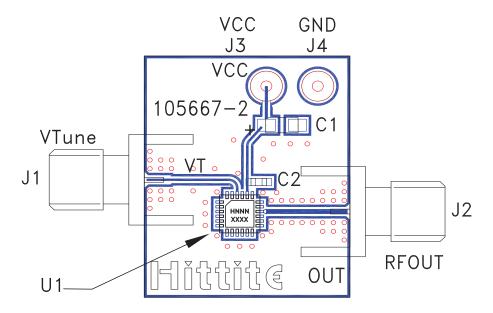
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1- 14, 17 - 19, 21, 23, 24	N/C	No Connection. These pins may be connected to RF ground. Performance will not be affected.	
15	GND	This pin must be connected to RF & DC ground.	→ GND —
16	RFOUT	RF output (AC coupled)	— —○ RFOUT
20	Vcc	Supply Voltage Vcc= 3V	Vcc O26pF
22	VTUNE	Control Voltage Input. Modulation port bandwidth dependent on drive source impedance.	VTUNE 0 1500 2.4pF
	GND	Package bottom has an exposed metal paddle that must be RF & DC grounded.	→ GND =



MMIC VCO w/ BUFFER AMPLIFIER, 6.8 - 7.4 GHz

Evaluation PCB



List of Materials for Evaluation PCB 105706 [1]

Item	Description	
J1 - J2	PCB Mount SMA RF Connector	
J3 - J4	DC Pin	
C1	4.7 μF Tantalum Capacitor	
C2	10,000 pF Capacitor, 0603 Pkg.	
U1	HMC505LP4 / HMC505LP4E VCO	
PCB [2]	105667 Eval Board	

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.

HMC505LP4 / 505LP4E

AMPLIFIER, 6.8 - 7.4 GHz

v02.0508



ANALOGDEVICES

Notes:

MMIC VCO w/ BUFFER

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Analog Devices Inc.:

HMC505LP4E HMC505LP4 HMC505LP4ETR 105706-HMC505LP4 HMC505LP4TR